

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	"10538402"	US-PGPUB; USPAT	OR	ON	2009/10/20 16:08
S2	11	"6586342"	US-PGPUB; USPAT	OR	ON	2009/10/31 09:04
S3	8	"6572742"	US-PGPUB; USPAT	OR	ON	2009/10/31 09:08
S4	6	((("6248222") or ("6391166") or ("6395152") or ("6440295") or ("6586342") or ("6572742")).PN.	US-PGPUB; USPAT	OR	OFF	2010/03/02 14:40
S5	68202	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro \$1plat\$3 or electro-plat \$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (wafer or substrate)	US-PGPUB; USPAT	OR	ON	2010/03/02 14:50
S6	4419	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro \$1plat\$3 or electro-plat \$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (wafer or substrate) and ((alignment or spac\$3 or center\$3) with (sens \$3 or monitor\$3 or detect\$3))	US-PGPUB; USPAT	OR	ON	2010/03/02 14:51

S7	1095	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro \$1plat\$3 or electro-plat \$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (wafer or substrate) and ((alignment or spac\$3 or center\$3) with (sens \$3 or monitor\$3 or detect\$3)) and @py<"2003"	US-PGPUB; USPAT	OR	ON	2010/03/02 14:52
S8	124	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro \$1plat\$3 or electro-plat \$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (wafer or substrate) and ((alignment or spac\$3 or center\$3) with (sens \$3 or monitor\$3 or detect\$3)) and @py<"2003" and ("204".clas. or "205". clas.)	US-PGPUB; USPAT	OR	ON	2010/03/02 14:52
S9	136	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro \$1plat\$3 or electro-plat \$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (wafer or substrate or workpiece) and ((alignment or spac\$3 or center\$3) with (sens \$3 or monitor\$3 or detect\$3)) and @py<"2003" and ("204".clas. or "205". clas.)	US-PGPUB; USPAT	OR	ON	2010/03/02 14:56

S10	238	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro \$1plat\$3 or electro-plat \$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (wafer or substrate or workpiece) and ((alignment or spac\$3 or center\$3 or position or distance) with (sens \$3 or monitor\$3 or detect\$3)) and @py<"2003" and ("204".clas. or "205". clas.)	US-PGPUB; USPAT	OR	ON	2010/03/02 15:18
S11	70	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro \$1plat\$3 or electro-plat \$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (wafer or substrate or workpiece) and ((alignment or spac\$3 or center\$3) with (sens \$3 or monitor\$3 or detect\$3)) and @py<"2003" and ("204".clas. or "205". clas.) and (semiconductor or wafer)	US-PGPUB; USPAT	OR	ON	2010/03/02 15:39
S12	0	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro \$1plat\$3 or electro-plat \$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (wafer or substrate or workpiece) and ((alignment or spac\$3 or center\$3) with (sens \$3 or monitor\$3 or detect\$3)) and @py<"2003" and ("204".clas. or "205". clas.) and (semiconductor or	EPO; JPO; DERWENT	OR	ON	2010/03/02 15:59

		wafer)				
S13	1	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (wafer or substrate or workpiece) and ((alignment or spac\$3 or center\$3) with (sens\$3 or monitor\$3 or detect\$3)) and @py<"2003" and (semiconductor or wafer)	EPO; JPO; DERWENT	OR	ON	2010/03/02 15:59
S14	14	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (wafer or substrate or workpiece) and ((alignment or spac\$3 or center\$3) with (sens\$3 or monitor\$3 or detect\$3)) and @py<"2003"	EPO; JPO; DERWENT	OR	ON	2010/03/02 15:59
S15	31	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (wafer or substrate or workpiece) and ((alignment or spac\$3 or center\$3 or position or distance) with (sens\$3 or monitor\$3 or detect\$3)) and @py<"2003"	EPO; JPO; DERWENT	OR	ON	2010/03/02 15:59
S16	231	batz.in.	US-PGPUB; USPAT	OR	ON	2010/03/02 16:06
S17	345786	batz.in. wafer	US-PGPUB; USPAT	OR	ON	2010/03/02 16:06

S18	43	batz.in. and wafer	US-PGPUB; USPAT	OR	ON	2010/03/02 16:07
S19	119	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro \$1plat\$3 or electro-plat \$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (wafer or substrate or workpiece) and ((alignment or spac\$3 or center\$3) with (sens \$3 or monitor\$3 or detect\$3)) and @py<"2005" and ("204".clas. or "205". clas.) and (semiconductor or wafer)	US-PGPUB; USPAT	OR	ON	2010/03/02 16:16
S20	49	S19 not S11	US-PGPUB; USPAT	OR	ON	2010/03/02 16:16
S21	613	((HUI) near2 (WANG)). INV.	US-PGPUB; USPAT	OR	ON	2010/03/29 13:59
S22	5	((VOHA) near2 (NUCH)).INV.	US-PGPUB; USPAT	OR	ON	2010/03/29 13:59
S23	139	((HUI) near2 (WANG)). INV.	EPO; JPO; DERWENT	OR	ON	2010/03/29 13:59
S24	13	((VOHA) near2 (NUCH)).INV.	EPO; JPO; DERWENT	OR	ON	2010/03/29 14:00
S25	33	"6294059"	US-PGPUB; USPAT	OR	ON	2010/03/29 14:04
S26	66	((HUI) near2 (WANG)). INV. and plating	US-PGPUB; USPAT	OR	ON	2010/03/29 14:10
S27	59	((HUI) near2 (WANG)). INV. and plating and (semiconductor or wafer or substrate)	US-PGPUB; USPAT	OR	ON	2010/03/29 14:11
S28	27	((HUI) near2 (WANG)). INV. and ("204".clas. or "205".clas.)	US-PGPUB; USPAT	OR	ON	2010/03/29 14:12
S29	35	((HUI) near2 (WANG)). INV. and (substrate or wafer or semiconductor or workpiece)	EPO; JPO; DERWENT	OR	ON	2010/03/29 14:13

S30	522239	(gap or align\$4 or spac\$3 or center\$3 or orintat\$3 or position\$3 or distance) with (monitor\$3 or measur\$4 or sens\$3 or detect\$3 or determin\$5) and (semiconductor or wafer or substrate or workpiece)	US-PGPUB; USPAT	OR	ON	2010/03/29 14:23
S31	288906	(gap or align\$4 or spac\$3 or center\$3 or orintat\$3 or position\$3 or distance) near2 (monitor\$3 or measur\$4 or sens\$3 or detect\$3 or determin\$5) and (semiconductor or wafer or substrate or workpiece)	US-PGPUB; USPAT	OR	ON	2010/03/29 14:23
S32	288906	((gap or align\$4 or spac\$3 or center\$3 or orintat\$3 or position\$3 or distance) near2 (monitor\$3 or measur\$4 or sens\$3 or detect\$3 or determin\$5)) and (semiconductor or wafer or substrate or workpiece)	US-PGPUB; USPAT	OR	ON	2010/03/29 14:23
S33	9028	((gap or align\$4 or spac\$3 or center\$3 or orintat\$3 or position\$3 or distance) near2 (monitor\$3 or measur\$4 or sens\$3 or detect\$3 or determin\$5)) and (semiconductor or wafer or substrate or workpiece) and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3)	US-PGPUB; USPAT	OR	ON	2010/03/29 14:24

S34	898	((gap or align\$4 or spac\$3 or center\$3 or orintat\$3 or position\$3 or distance) near2 (monitor\$3 or measur\$4 or sens\$3 or detect\$3 or determin\$5)) and (semiconductor or wafer or substrate or workpiece) and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and ("204".clas. or "205".clas.)	US-PGPUB; USPAT	OR	ON	2010/03/29 14:24
S35	277	((gap or align\$4 or spac\$3 or center\$3 or orintat\$3 or position\$3 or distance) near2 (monitor\$3 or measur\$4 or sens\$3 or detect\$3 or determin\$5)) and (semiconductor or wafer or substrate or workpiece) and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and ("204".clas. or "205".clas.) and @py< "2002"	US-PGPUB; USPAT	OR	ON	2010/03/29 14:25
S36	170	((gap or align\$4 or spac\$3 or center\$3 or orintat\$3 or position\$3 or distance) near1 (monitor\$3 or measur\$4 or sens\$3 or detect\$3 or determin\$5)) and (semiconductor or wafer or substrate or workpiece) and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro	US-PGPUB; USPAT	OR	ON	2010/03/29 14:26

		\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and ("204".clas. or "205".clas.) and @py<"2002"				
S37	0	((gap or align\$4 or spac\$3 or center\$3 or orintat\$3 or position\$3 or distance) near1 (monitor\$3 or measur\$4 or sens\$3 or detect\$3 or determin\$5)) with chuck) and (semiconductor or wafer or substrate or workpiece) and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and ("204".clas. or "205".clas.) and @py<"2002"	US-PGPUB; USPAT	OR	ON	2010/03/29 14:53
S38	6	((gap or align\$4 or spac\$3 or center\$3 or orintat\$3 or position\$3 or distance) near1 (chuck)) and (semiconductor or wafer or substrate or workpiece) and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and ("204".clas. or "205".clas.) and @py<"2002"	US-PGPUB; USPAT	OR	ON	2010/03/29 14:54

S39	0	((gap or align\$4 or spac\$3 or center\$3 or orintat\$3 or position\$3 or distance) near1 (chuck)) and (semiconductor or wafer or substrate or workpiece) and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and ("204".clas. or "205".clas.) and @py<"2002"	USOCR; EPO; JPO	OR	ON	2010/03/29 14:58
S40	34	((gap or align\$4 or spac\$3 or center\$3 or orintat\$3 or position\$3 or distance) near1 (monitor\$3 or measur\$4 or sens\$3 or detect\$3 or determin\$5)) and (semiconductor or wafer or substrate or workpiece) and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and ("204".clas. or "205".clas.) and @py<"2002"	USOCR; EPO; JPO; DERWENT	OR	ON	2010/03/29 14:58
S41	32964	((gap or align\$4 or spac\$3) near1 (monitor\$3 or measur\$4 or sens\$3 or detect\$3 or determin\$5)) and @py<"2002"	USOCR; EPO; JPO; DERWENT	OR	ON	2010/03/29 15:23
S42	6229	((align\$4) near1 (monitor\$3 or measur\$4 or sens\$3 or detect\$3 or determin\$5)) and @py<"2002"	USOCR; EPO; JPO; DERWENT	OR	ON	2010/03/29 15:24

S43	180	((align\$4) near1 (monitor\$3 or measur \$4 or sens\$3 or detect \$3 or determin\$5)) and @py<"2002" and tolerance	USOCR; EPO; JPO; DERWENT	OR	ON	2010/03/29 15:24
S44	77	((align\$4) near1 (monitor\$3 or measur \$4 or sens\$3 or detect \$3 or determin\$5)) and @py<"2002" and tolerance and (optical or magnetic or capacitance or ultrasonic)	USOCR; EPO; JPO; DERWENT	OR	ON	2010/03/29 15:25
S45	1610	((align\$4) near1 (monitor\$3 or measur \$4 or sens\$3 or detect \$3 or determin\$5)) and @py<"2002" and tolerance and (optical or magnetic or capacitance or ultrasonic)	US-PGPUB; USPAT	OR	ON	2010/03/29 15:25
S46	1347	((align\$4) near1 (monitor\$3 or measur \$4 or sens\$3 or detect \$3)) and @py<"2002" and tolerance and (optical or magnetic or capacitance or ultrasonic)	US-PGPUB; USPAT	OR	ON	2010/03/29 15:26
S47	20	((align\$4) near1 (monitor\$3 or measur \$4 or sens\$3 or detect \$3)) and @py<"2002" and tolerance and (optical or magnetic or capacitance or ultrasonic) and ("204". clas. or "205".clas.)	US-PGPUB; USPAT	OR	ON	2010/03/29 15:26
S48	45	((align\$4) near1 (monitor\$3 or measur \$4 or sens\$3 or detect \$3)) and @py<"2002" and tolerance and (optical or magnetic or capacitance or ultrasonic) and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro \$1plat\$3 or electro-plat	US-PGPUB; USPAT	OR	ON	2010/03/29 15:28

		\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3)				
S49	67	((align\$4) near1 (monitor\$3 or measur \$4 or sens\$3 or detect \$3)) and @py<"2003" and tolerance and (optical or magnetic or capacitance or ultrasonic) and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro \$1plat\$3 or electro-plat \$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3)	US-PGPUB; USPAT	OR	ON	2010/03/29 15:28
S50	0	((align\$4) near1 (monitor\$3 or measur \$4 or sens\$3 or detect \$3)) and @py<"2003" and tolerance and (optical or magnetic or capacitance or ultrasonic) and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro \$1plat\$3 or electro-plat \$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3)	JPO	OR	ON	2010/03/29 15:34
S51	0	((align\$4) with (monitor \$3 or measur\$4 or sens \$3 or detect\$3)) and @py<"2003" and tolerance and (optical or magnetic or capacitance or ultrasonic) and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro \$1plat\$3 or electro-plat \$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3)	JPO	OR	ON	2010/03/29 15:34

S52	244	((align\$4) with (monitor\$3 or measur\$4 or sens\$3 or detect\$3)) and @py< "2003" and tolerance and (optical or magnetic or capacitance or ultrasonic) and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3)	US-PGPUB; USPAT	OR	ON	2010/03/29 15:34
S53	119	((align\$4) with (monitor\$3 or measur\$4 or sens\$3 or detect\$3)) same (chuck or wafer or substrate or chip or semiconductor or workpiece) and @py< "2003" and tolerance and (optical or magnetic or capacitance or ultrasonic) and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3)	US-PGPUB; USPAT	OR	ON	2010/03/29 15:35
S54	62583	((align\$4) with (chuck or wafer or substrate or chip or semiconductor or workpiece)) and @py< "2003"	US-PGPUB; USPAT	OR	ON	2010/03/29 16:09
S55	3464	((align\$4) with (chuck or wafer or substrate or chip or semiconductor or workpiece)) and @py< "2003" and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3)	US-PGPUB; USPAT	OR	ON	2010/03/29 16:10

S56	2500	((align\$4) with (chuck or wafer or substrate or chip or semiconductor or workpiece)) and @py< "2002" and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3)	US-PGPUB; USPAT	OR	ON	2010/03/29 16:10
S57	1218	((align\$4) near2 (chuck or wafer or substrate or chip or semiconductor or workpiece)) and @py< "2002" and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3)	US-PGPUB; USPAT	OR	ON	2010/03/29 16:10
S58	673	((align\$4) near2 (chuck or wafer or substrate or chip or semiconductor or workpiece)) and @py< "2002" and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (sens\$3 or detect\$3 or monitor\$3 or measur\$4)	US-PGPUB; USPAT	OR	ON	2010/03/29 16:11
S59	498	((align\$4) near2 (chuck or wafer or substrate or chip or semiconductor or workpiece)) and @py< "2002" and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3)	US-PGPUB; USPAT	OR	ON	2010/03/29 16:11

		and (sens\$3 or detect\$3 or monitor\$3 or measur\$4) and (optical or magnetic or capacitance or ultrasonic)				
S60	305	((align\$4) near1 (chuck or wafer or substrate or chip or semiconductor or workpiece)) and @py<"2002" and (electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (sens\$3 or detect\$3 or monitor\$3 or measur\$4) and (optical or magnetic or capacitance or ultrasonic)	US-PGPUB; USPAT	OR	ON	2010/03/29 16:12
S61	4	"6579149"	US-PGPUB; USPAT	OR	ON	2010/03/29 16:16
S62	24	("0034425" "20020052126" "4998021" "5081796" "5220405" "5433650" "5461007" "5492594" "5640242" "5777739" "5856871" "5872633" "5936733" "5948203" "5949927" "5958148" "5961369" "5999264" "6020264" "6319093").PN. OR ("6579149").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/29 16:18
S63	33	"4934064"	US-PGPUB; USPAT	OR	ON	2010/03/29 16:29

S64	1487	((align\$4) with (monitor\$3 or measur\$4 or sens\$3 or detect\$3)) same (chuck or wafer or substrate or chip or semiconductor or workpiece) and @py<"2003" and tolerance and (optical or magnetic or capacitance or ultrasonic)	US-PGPUB; USPAT	OR	ON	2010/03/30 09:18
S65	659	((align\$4) near2 (monitor\$3 or measur\$4 or sens\$3 or detect\$3)) same (chuck or wafer or substrate or chip or semiconductor or workpiece) and @py<"2003" and tolerance and (optical or magnetic or capacitance or ultrasonic)	US-PGPUB; USPAT	OR	ON	2010/03/30 09:19
S66	129	("4449885" "4507078" "4523985" "4647266" "4705951" "4720635").PN. OR ("4819167").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/30 09:21
S67	76	("20020038164" "20020078770" "20020092369" "20020101508" "20030001083" "20030115978" "20030127589" "20030198376" "20030202092" "20030209097" "20040031340" "20040236524" "20050011611" "20050028049" "20050039852" "20050126315" "20070022832" "4119381" "4180199" "4365705" "4543576" "4745564" "4819167" "4821674" "5046909" "5321634" "5321989" "5435682" "5444637"	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/30 09:26

		"5445491" "5452521" "5483138" "5521123" "5552891" "5573728" "5625297" "5726066" "5746513" "5775808" "5786704" "5844683" "5851370" "5917601" "5929689" "5942991" "5946083" "5962909" "5967661" "5969639" "5980194" "5993141" "6002840" "6048162" "6051113" "6111520" "6195246" "6198176" "6208751" "6244121" "6313596" "6352466" "6368049" "6468816" "6517418" "6532403" "6542835" "6603117" "6642853" "6648730" "6677166" "6691068" "6723981" "6738722" "6830650" "6871660" "7192505").PN. OR ("7434485").URPN.				
S68	6	("4819167" "4880348" "5851102" "6062084" "6298280").PN. OR ("6943364").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/30 09:46
S69	83	("4697089" "4770590" "4819167" "4836733" "5054991" "5194743" "5483138").PN. OR ("5563798").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/30 10:33
S70	2919	((align\$4) near2 (monitor\$3 or measur \$4 or sens\$3 or detect \$3)) same (chuck or wafer or substrate or chip or semiconductor or workpiece) and @py< "2003" and (optical or magnetic or capacitance or ultrasonic)	US-PGPUB; USPAT	OR	ON	2010/03/30 10:56

S71	2158	((alignment) near2 (monitor\$3 or measur \$4 or sens\$3 or detect \$3)) same (chuck or wafer or substrate or chip or semiconductor or workpiece) and @py<"2003" and (optical or magnetic or capacitance or ultrasonic)	US-PGPUB; USPAT	OR	ON	2010/03/30 10:57
S72	1624	((alignment) near2 (monitor\$3 or measur \$4 or sens\$3 or detect \$3)) with (chuck or wafer or substrate or chip or semiconductor or workpiece) and @py<"2003" and (optical or magnetic or capacitance or ultrasonic)	US-PGPUB; USPAT	OR	ON	2010/03/30 10:57
S73	825	((alignment) near2 (monitor\$3 or measur \$4 or sens\$3 or detect \$3)) with (chuck or wafer or substrate or chip or semiconductor or workpiece) same (optical or magnetic or capacitance or ultrasonic) and @py<"2003"	US-PGPUB; USPAT	OR	ON	2010/03/30 10:57
S74	623	((alignment) near2 (monitor\$3 or measur \$4 or sens\$3 or detect \$3)) with (chuck or wafer or substrate or chip or semiconductor or workpiece) same (optical or magnetic or capacitance or ultrasonic) and @py<"2002"	US-PGPUB; USPAT	OR	ON	2010/03/30 10:57
S75	427	(alignment) and (optical or magnetic or capacitance or ultrasonic) and @py<"2002" and "269". clas.	US-PGPUB; USPAT	OR	ON	2010/03/30 11:22

S76	24675	(polishing or plating or electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (cup or fountain or (face near1 down) or (face near1 up))	US-PGPUB; USPAT	OR	ON	2010/03/30 11:38
S77	18943	(polishing or plating or electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (cup or fountain or (face near1 down) or (face near1 up)) and (wafer or semiconductor or substrate or chip or workpiece)	US-PGPUB; USPAT	OR	ON	2010/03/30 11:38
S78	5809	(polishing or plating or electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (cup or fountain or (face near1 down) or (face near1 up)) and (wafer or semiconductor or substrate or chip or workpiece) and @py<"2003"	US-PGPUB; USPAT	OR	ON	2010/03/30 11:38

S79	3933	(polishing or plating or electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (cup or fountain or (face near1 down) or (face near1 up)) and (wafer or semiconductor or substrate or chip or workpiece) and @py<"2003" and (chuck or receptacle or tank or cup)	US-PGPUB; USPAT	OR	ON	2010/03/30 11:39
S80	3162	(polishing or plating or electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (cup or fountain or (face near1 down) or (face near1 up)) and (wafer or semiconductor or substrate or chip or workpiece) and @py<"2003" and (chuck or receptacle or tank or cup) and (align \$4 or position\$3 or center\$3)	US-PGPUB; USPAT	OR	ON	2010/03/30 11:40
S81	3341	(polishing or plating or electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (cup or fountain or (face near1 down) or (face near1 up)) and (wafer or semiconductor or substrate or chip or	US-PGPUB; USPAT	OR	ON	2010/03/30 11:40

		workpiece) and @py< "2003" and (chuck or receptacle or tank or cup) and (align \$4 or position\$3 or center\$3 or spac\$3)				
S82	2251	(polishing or plating or electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro \$1plat\$3 or electro-plat \$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (cup or fountain or (face near1 down) or (face near1 up)) and (wafer or semiconductor or substrate or chip or workpiece) and @py< "2003" and (chuck or receptacle or tank or cup) and (align \$4 or position\$3 or center\$3 or spac\$3) and (electrolyte or solution or bath)	US-PGPUB; USPAT	OR	ON	2010/03/30 11:40
S83	1811	(polishing or plating or electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro \$1plat\$3 or electro-plat \$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (cup or fountain or (face near1 down) or (face near1 up)) and (wafer or semiconductor or substrate or chip or workpiece) and @py< "2003" and (chuck or receptacle or tank or cup) and (align \$4 or position\$3 or center\$3 or spac\$3) and (electrolyte or solution or bath) and (sens\$3 or detect\$3 or monit\$3 or measur\$4)	US-PGPUB; USPAT	OR	ON	2010/03/30 11:42

S84	1022	(polishing or plating or electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (cup or fountain or (face near1 down) or (face near1 up)) and (wafer or semiconductor or substrate or chip or workpiece) and @py<"2003" and (chuck or receptacle or tank or cup) and (align\$4 or position\$3 or center\$3 or spac\$3) and (electrolyte or solution or bath) and (sens\$3 or detect\$3 or monit\$3 or measur\$4) and (optical or magnetic or capacitance or ultrasonic)	US-PGPUB; USPAT	OR	ON	2010/03/30 11:43
S85	525	(polishing or plating or electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (cup or fountain or (face near1 down) or (face near1 up)) and (wafer or semiconductor or substrate or chip or workpiece) and @py<"2003" and (chuck or receptacle or tank or cup) and (align\$4 or position\$3 or center\$3 or spac\$3) and (electrolyte or solution or bath) and ((sens\$3 or detect\$3 or monit\$3 or measur\$4) same (optical or magnetic or	US-PGPUB; USPAT	OR	ON	2010/03/30 11:43

		capacitance or ultrasonic))				
S86	193	(polishing or plating or electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (cup or fountain or (face near1 down) or (face near1 up)) and (wafer or semiconductor or substrate or chip or workpiece) and @py<"2003" and ((chuck or receptacle or tank or cup) same (align\$4 or position\$3 or center\$3 or spac\$3)) and (electrolyte or solution or bath) and ((sens\$3 or detect\$3 or monit\$3 or measur\$4) same (optical or magnetic or capacitance or ultrasonic))	US-PGPUB; USPAT	OR	ON	2010/03/30 11:44
S87	118	(polishing or plating or electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (cup or fountain or (face near1 down) or (face near1 up)) and @py<"2003" and ((chuck or receptacle or tank or cup) same (align\$4 or position\$3 or center\$3 or spac\$3) same (wafer or semiconductor or substrate or chip or workpiece)) and (electrolyte or solution or bath) and ((sens\$3 or detect\$3 or monit\$3 or measur\$4) same	US-PGPUB; USPAT	OR	ON	2010/03/30 13:29

		(optical or magnetic or capacitance or ultrasonic))				
S88	45	(polishing or plating or electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (cup or fountain or (face near1 down) or (face near1 up)) and @py<"2003" and ((chuck or receptacle or tank or cup) same (align\$4 or position\$3 or center\$3 or spac\$3) same (wafer or semiconductor or substrate or chip or workpiece)) and (electrolyte or solution or bath) and ((sens\$3 or detect\$3 or monit\$3 or measur\$4) same (optical or magnetic or capacitance or ultrasonic)) and tolerance	US-PGPUB; USPAT	OR	ON	2010/03/30 13:29
S89	31	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and (cup or fountain or (face near1 down) or (face near1 up)) and @py<"2003" and ((chuck or receptacle or tank or cup) same (align\$4 or position\$3 or center\$3 or spac\$3) same (wafer or semiconductor or substrate or chip or workpiece)) and (electrolyte or solution or bath) and ((sens\$3 or detect\$3 or monit\$3 or measur\$4) same	US-PGPUB; USPAT	OR	ON	2010/03/30 13:30

		(optical or magnetic or capacitance or ultrasonic)) and tolerance				
S90	64	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and @py<"2003" and ((chuck or receptacle or tank or cup) same (align\$4 or position\$3 or center\$3 or spac\$3) same (wafer or semiconductor or substrate or chip or workpiece)) and (electrolyte or solution or bath) and ((sens\$3 or detect\$3 or monit\$3 or measur\$4) same (optical or magnetic or capacitance or ultrasonic)) and tolerance	US-PGPUB; USPAT	OR	ON	2010/03/30 13:30
S91	161	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and @py<"2003" and ((chuck or receptacle or tank or cup) same (align\$4 or position\$3 or center\$3 or spac\$3) same (wafer or semiconductor or substrate or chip or workpiece)) and (electrolyte or solution or bath) and ((sens\$3 or detect\$3 or monit\$3 or measur\$4) same (optical or magnetic or capacitance or ultrasonic))	US-PGPUB; USPAT	OR	ON	2010/03/30 13:33

S92	156	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3) and @py<"2003" and ((chuck or receptacle or tank or cup) same (align\$4 or position\$3 or center\$3 or spac\$3) same (wafer or semiconductor or substrate or chip or workpiece)) and (electrolyte or solution or bath) and ((sens\$3 or detect\$3 or monit\$3 or measur\$4) same (optical or magnetic or capacitance or ultrasonic))	US-PGPUB; USPAT	OR	ON	2010/03/30 13:33
S93	155	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3) and @py<"2003" and ((chuck or receptacle or tank or cup) same (align\$4 or position\$3 or center\$3 or spac\$3) same (wafer or semiconductor or substrate or workpiece)) and (electrolyte or solution or bath) and ((sens\$3 or detect\$3 or monit\$3 or measur\$4) same (optical or magnetic or capacitance or ultrasonic))	US-PGPUB; USPAT	OR	ON	2010/03/30 13:33
S94	154	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3) and @py<"2003" and ((chuck or receptacle or tank or cup) same (align\$4 or position\$3 or center\$3 or spac\$3) same (wafer or substrate or workpiece)) and	US-PGPUB; USPAT	OR	ON	2010/03/30 13:34

		(electrolyte or solution or bath) and ((sens\$3 or detect\$3 or monit\$3 or measur\$4) same (optical or magnetic or capacitance or ultrasonic))				
S95	145	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3) and @py<"2003" and ((chuck or receptacle or tank or cup) same (align\$4 or position\$3 or center\$3 or spac\$3) same (wafer or substrate)) and (electrolyte or solution or bath) and ((sens\$3 or detect\$3 or monit\$3 or measur\$4) same (optical or magnetic or capacitance or ultrasonic))	US-PGPUB; USPAT	OR	ON	2010/03/30 13:34
S96	57	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3) and @py<"2003" and ((chuck or receptacle or tank or cup) same (align\$4 or position\$3 or center\$3 or spac\$3) near2 (wafer or substrate)) and (electrolyte or solution or bath) and ((sens\$3 or detect\$3 or monit\$3 or measur\$4) same (optical or magnetic or capacitance or ultrasonic))	US-PGPUB; USPAT	OR	ON	2010/03/30 13:41

S97	37	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3) and @py<"2003" and ((chuck or receptacle or tank or cup) same (align\$4 or center\$3 or spac\$3) near2 (wafer or substrate)) and (electrolyte or solution or bath) and ((sens\$3 or detect\$3 or monit\$3 or measur\$4) same (optical or magnetic or capacitance or ultrasonic))	US-PGPUB; USPAT	OR	ON	2010/03/30 13:42
S98	37	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3) and @py<"2003" and ((chuck or receptacle or tank or cup) same (align\$4 or center\$3) near2 (wafer or substrate)) and (electrolyte or solution or bath) and ((sens\$3 or detect\$3 or monit\$3 or measur\$4) same (optical or magnetic or capacitance or ultrasonic))	US-PGPUB; USPAT	OR	ON	2010/03/30 13:42
S99	139	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3) and @py<"2003" and ((aligning or alignment or centering) near2 (wafer or substrate or chuck)) and (electrolyte or solution or bath) and ((sens\$3 or detect\$3 or monit\$3 or measur\$4) same (optical or magnetic or capacitance or ultrasonic))	US-PGPUB; USPAT	OR	ON	2010/03/30 13:45

S100	71	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro \$1plat\$3 or electro-plat \$3) and @py<"2003" and ((aligning or alignment or centering) near1 (wafer or substrate or chuck)) and (electrolyte or solution or bath) and ((sens\$3 or detect\$3 or monit\$3 or measur\$4) same (optical or magnetic or capacitance or ultrasonic))	US-PGPUB; USPAT	OR	ON	2010/03/30 13:45
S101	185	(electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro \$1plat\$3 or electro-plat \$3) and @py<"2003" and ((aligning or alignment or centering) near1 (wafer or substrate or chuck)) and (electrolyte or solution or bath)	US-PGPUB; USPAT	OR	ON	2010/03/30 13:46
S102	222	205/81.ccls.	US-PGPUB; USPAT	OR	ON	2010/03/30 14:07
S103	120	205/652.ccls.	US-PGPUB; USPAT	OR	ON	2010/03/30 14:08
S104	642	(polishing or plating or electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro \$1plat\$3 or electro-plat \$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and @py<"2003" and ((chuck or receptacle or tank or cup) and (align \$4 or position\$3 or center\$3 or spac\$3) and (wafer or semiconductor or substrate or chip or workpiece))	EPO; JPO; DERWENT	OR	ON	2010/03/30 14:14

S105	374	(polishing or plating or electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and @py<"2003" and ((chuck or receptacle or tank or cup) with (align\$4 or position\$3 or center\$3 or spac\$3) and (wafer or semiconductor or substrate or chip or workpiece))	EPO; JPO; DERWENT	OR	ON	2010/03/30 14:15
S106	310	(polishing or plating or electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and @py<"2003" and ((chuck or receptacle or tank or cup) with (align\$4 or position\$3 or center\$3 or spac\$3) same (wafer or semiconductor or substrate or chip or workpiece))	EPO; JPO; DERWENT	OR	ON	2010/03/30 14:15
S107	248	(polishing or plating or electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and @py<"2003" and ((chuck or receptacle or tank or cup) with (align\$4 or position\$3 or center\$3 or spacing) same (wafer or semiconductor or substrate or chip or workpiece))	EPO; JPO; DERWENT	OR	ON	2010/03/30 14:19

S108	104	(polishing or plating or electropolish\$3 or electro\$1polish\$3 or electro-polish\$3 or electroplat\$3 or electro\$1plat\$3 or electro-plat\$3 or electrodeposit\$3 or electro-deposit\$3 or electro\$1deposit\$3) and @py<"2003" and ((chuck or receptacle or tank or cup) with (align\$4 or positioning or center\$3 or spacing) same (wafer or semiconductor or substrate or chip or workpiece))	EPO; JPO; DERWENT	OR	ON	2010/03/30 14:21
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